IN THE CLAIMS:

Please amend the claims as shown below. The status of the claims after amendment will be as follows:

1. (currently amended) A lead-free solder comprising 1.5 - 8 mass % of Cu, 0.01 - 2 mass % of Co, 0 - 1 mass % of Ni, and a remainder of Sn and having a liquidus temperature of 420°C or below, no element in the solder other than Sn or Cu having a content of greater than 2 mass %.

2. (original) A lead-free solder as claimed in claim 1 wherein the Ni content is 0.01 - 1 mass %.

3. (original) A lead-free solder as claimed in claim 1 which further comprises at least one oxidation-inhibiting element.

4. (original) A lead-free solder as claimed in claim 3 wherein the at least one oxidation-inhibiting element is selected from the group consisting of P, Ge, and Ga, with the total amount of these elements being 0.001 - 0.5 mass %.

5. (original) A lead-free solder as claimed in claim 1 which further comprises at least one wettability-improving element.

6. (original) A lead-free solder as claimed in claim 5 wherein the at least one wettability-improving element comprises Ag in an amount of 0.05 - 2 mass %.

7. (original) A coil comprising a wire with an end which is precoated with a lead-free solder as claimed in claim 1.

8. (original) A soldered joint comprising a lead-free solder as claimed in claim 1.

9. (original) A solder method comprising soldering the precoated end of the coil as claimed in claim 7 to another member.

10. (original) A method of treating a copper wire comprising dipping an end of a coated copper wire in molten solder comprising a solder as claimed in claim 1.

Claim 11 (cancelled)

12. (previously presented) A lead-free solder as claimed in claim 1 wherein the solder consists essentially of 1.5 - 8 mass % of Cu, 0.01 - 2 mass % of Co, 0.01 - 1 mass % of Ni, and a remainder of Sn.

13. (previously presented) A lead-free solder as claimed in claim 1 wherein the solder consists essentially of 1.5 - 8

mass % of Cu, 0.01 - 2 mass % of Co, 0.01 - 1 mass % of Ni, 0.05 - 2 mass % of Ag, and a remainder of Sn.

14. (currently amended) A coil comprising a wire with an end which is precoated with a lead-free solder as claimed in claim ~~11~~ 12.

15. (currently amended) A method of treating a copper wire comprising dipping an end of a coated copper wire in molten solder comprising a solder as claimed in claim ~~11~~ 12.

Claim 16 (cancelled)

17. (previously presented) A lead-free solder as claimed in claim 1 wherein the solder consists of 1.5 - 8 mass % of Cu, 0.01 - 2 mass % of Co, 0.01 - 1 mass % of Ni, and a remainder of Sn.